

IN THE CLAIMS:

Please amend the claims as follows:

1 (withdrawn). A hermetic package, comprising:

an bottom portion;

a top portion to mate over said bottom portion at a seam to form a package;

a fiber feed through;

an optical fiber having a first portion inside said package and a second portion outside said package extending through said feed through;

a laser weld joint at said seam; and

a reflowed glass solder inside of said feed through coaxial with said fiber.

2 (withdrawn). A hermetic package as recited in claim 1 wherein said feed through comprises:

a top half formed with said top portion; and

a bottom half formed with said bottom portion.

3 (withdrawn). A hermetic package as recited in claim 2 wherein said top portion and said bottom portion comprise Kovar.

4 (withdrawn). A hermetic package as recited in claim 2 wherein said hermetic package encases an optoelectronic device.

5 (withdrawn). A hermetic package as recited in claim 1 wherein said seam is approximately in a plane of said optical fiber.

6 (withdrawn). A hermetic package as recited in claim 1 wherein said reflowed glass solder is reflowed by one of said laser heating, induction heating, and resistive heating.

7-12 (cancelled)

13 (withdrawn). A hermetically sealed optoelectronic package, comprising:

- a bottom for said package;

- a top for said package to mate over said bottom at a seam;

- a fiber feed through;

- optoelectronic components in said package;

- an optical fiber having a first portion aligned with said components in said package and a second portion extending outside said package through said fiber feed through;

- a laser weld joint said seam; and

a reflowed glass solder inside of said fiber feed through coaxial with said fiber.

14 (withdrawn). A hermetically sealed optoelectronic package, as recited in claim 13 wherein said fiber feed through is formed integrally with said top and said bottom.

15 (withdrawn). A hermetically sealed optoelectronic package, as recited in claim 13 wherein said top and said bottom comprises a metallic alloy.

16 (withdrawn). A hermetically sealed optoelectronic package, as recited in claim 15 wherein said metallic alloy comprises Kovar.

17 (withdrawn). A hermetically sealed optoelectronic package, as recited in claim 14 wherein said seam comprises a laser weld.

18 (withdrawn). A hermetically sealed optoelectronic package, as recited in claim 17 wherein said glass ring is reflowed by laser heating.

19 (withdrawn). A hermetically sealed optoelectronic package, as recited in claim 17 wherein said glass ring is reflowed by one of resistive heating and induction heating.

20 (withdrawn). A hermetically sealed optoelectronic package, as recited in claim 13 wherein said seam is approximately in a plane of said optical fiber.

21 (original). A hermetic package, comprising:

- a package bottom having a first generally semi-cylindrical snout;

- an optical fiber having a first portion inside said package bottom and a second portion outside said package bottom through said semi-cylindrical snout;

- a package top having a second generally semi-cylindrical snout to mate over said package bottom at a seam to form a package having a cylindrical snout;

- a laser weld joint at said seam;

- solder to seal between said snout and said optical fiber;

- a furcation tube on said second portion of said optical fiber;

- a coupling tube around said cylindrical snout and said furcation tube;

and

- an epoxy to seal and area inside said coupling tube.

22 (original). A hermetic package as recited in claim 21 wherein said coupling tube comprises an opening for introducing said epoxy.

23 (original). A hermetic package as recited in claim 22 further comprising a strain relief boot over said coupling tube and said furcation tube.

24 (original). A hermetic package as recited in claim 21 wherein said solder comprises a glass solder.

25 (original). A hermetic package as recited in claim 24 wherein said fiber comprises one of a 250, 400, and 900 micron fiber.

26-28 (cancelled).

29 (original). A hermetic package, comprising:

- a package bottom having a first generally semi-circular notch;

- an optical fiber having a first portion inside said package bottom and a second portion outside said package bottom through said semi-circular notch;

- a package top having a second generally semi-circular notch to mate over said package bottom at a seam to form a package having a circular opening;

- a generally cylindrical snout having a lip to fit inside said circular opening;

- a laser weld joint at said seam and around said circular opening;

- a first opening in said snout to solder seal between said snout and said

optical fiber;

a furcation tube around said optical fiber extending into said snout; and

a second opening in said snout to introduce epoxy into an area inside
said snout.

30 (original). A hermetic package as recited in claim 29, further comprising:

a strain relief boot over said snout and said furcation tube.

31 (original). A hermetic package as recited in claim 29 wherein said solder is
one of glass solder and metal alloy solder.

32-34 (cancelled).